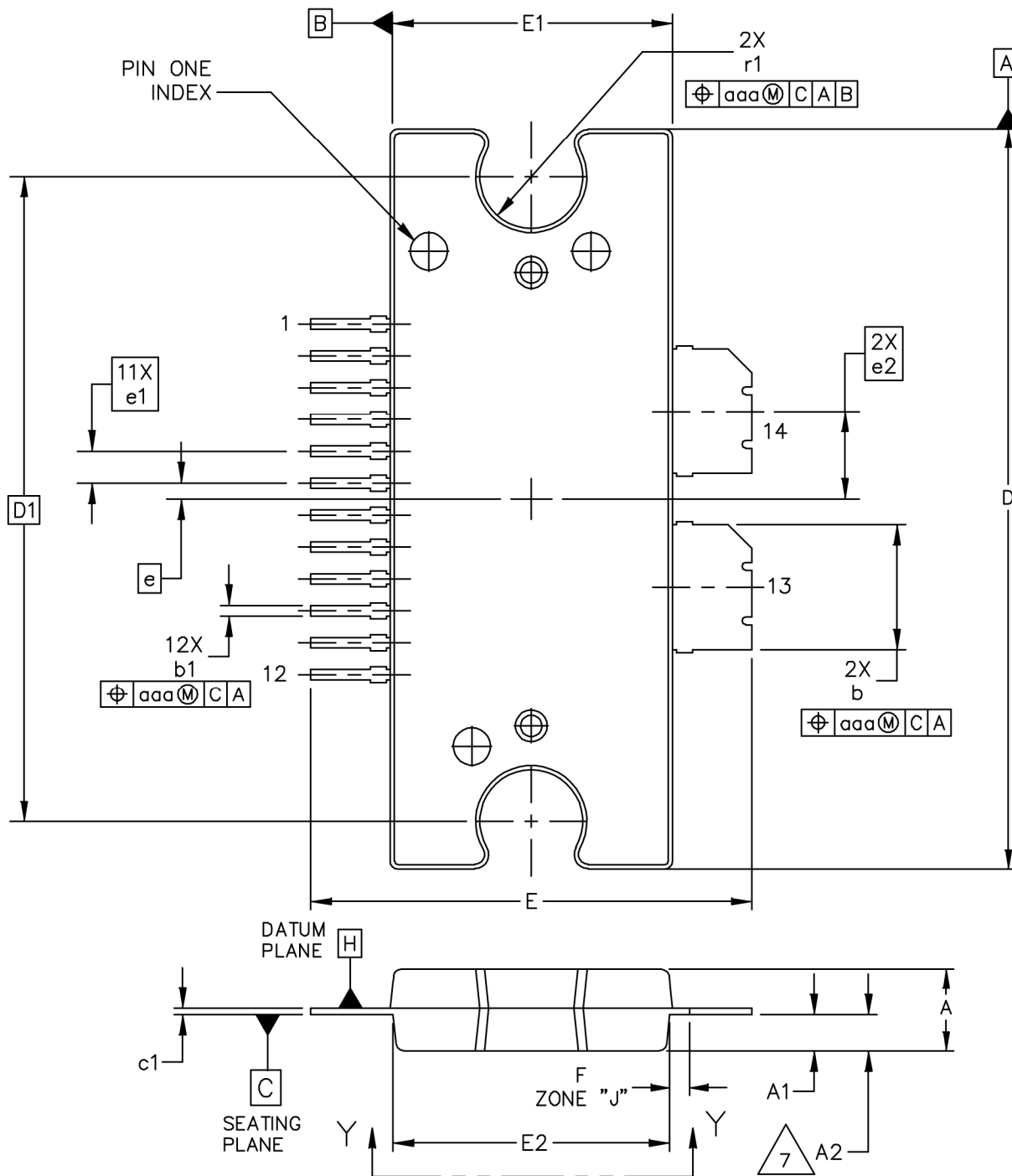
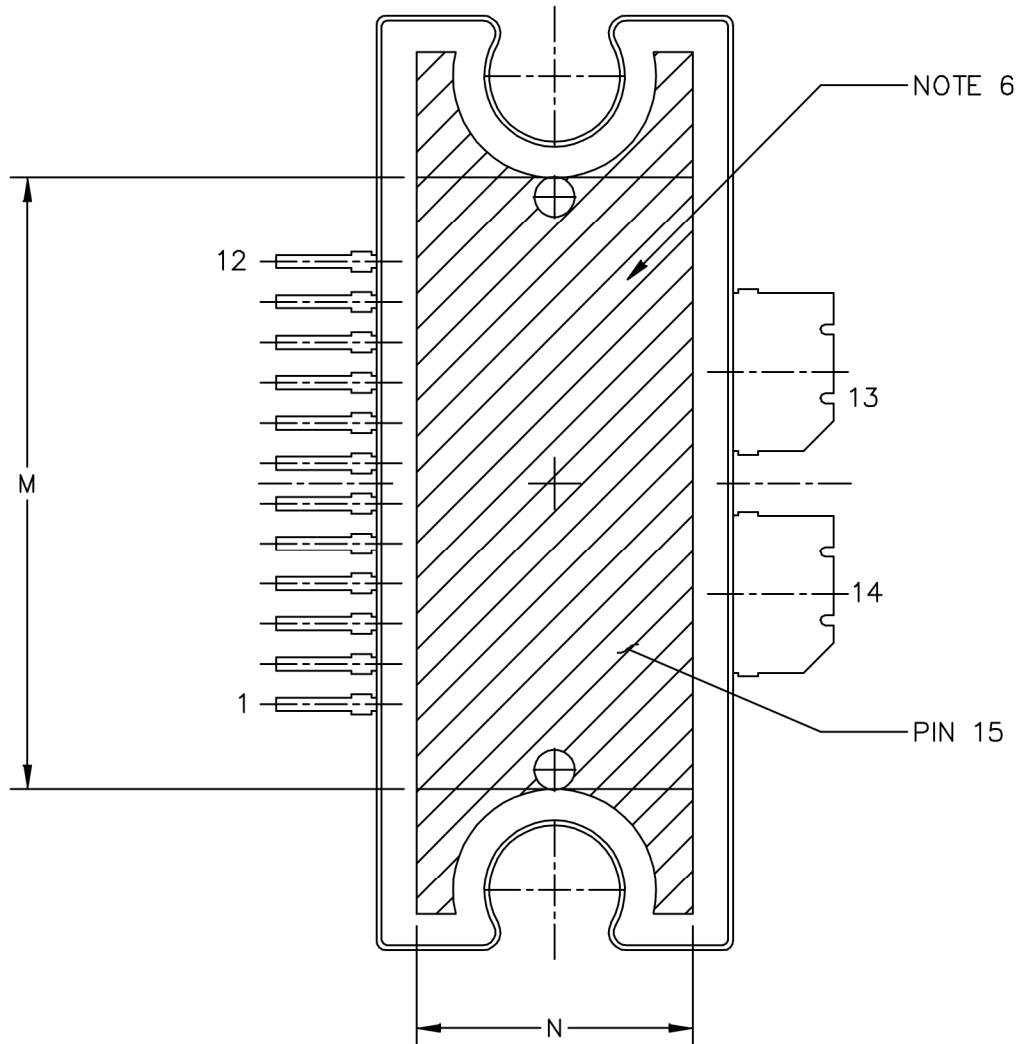


PACKAGE DIMENSIONS



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TITLE: TO-272 WIDE BODY 14 LEAD		DOCUMENT NO: 98ASA10649D	REV: A
		CASE NUMBER: 1617-02	27 JUN 2007
		STANDARD: NON-JEDEC	



VIEW Y-Y

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MD7IC2050NR1 MD7IC2050GNR1 MD7IC2050NBR1

NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 (0.15) PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS "b" AND "b1" DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 (0.13) TOTAL IN EXCESS OF THE "b" AND "b1" DIMENSIONS AT MAXIMUM MATERIAL CONDITION.
6. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.
7. DIM A2 APPLIES WITHIN ZONE "J" ONLY.

INCH		MILLIMETER		INCH		MILLIMETER	
DIM	MIN	MAX	MIN	MAX	DIM	MIN	MAX
A	.100	.104	2.54	2.64	b	.154	.160
A1	.039	.043	0.99	1.09	b1	.010	.016
A2	.040	.042	1.02	1.07	c1	.007	.011
D	.928	.932	23.57	23.67	e	.020 BSC	0.51 BSC
D1	.810 BSC		20.57 BSC		e1	.040 BSC	1.02 BSC
E	.551	.559	14.00	14.20	e2	.1105 BSC	2.807 BSC
E1	.353	.357	8.97	9.07	r1	.063	.068
E2	.346	.350	8.79	8.89			
F	.025 BSC		0.64 BSC		aaa	.004	0.10
M	.600	----	15.24	----			
N	.270	----	6.86	----			
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